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□	□	US 6485915 R1	20021217	17	Flip chip package of monolithic microelectronic semiconductor	2571
□	□	US 6485918 R2	20021217	15	Semiconductor clamped stack assembly	2571
□	□	US 6483188 R1	20021119	6	RF integrated circuit layout	2571
□	□	US 6476484 R1	20021105	7	Heat sink dissipator for antineutrino thickener channel	2571
□	□	US 6472748 R1	20021029	9	System and method for nonvolatile MMIC seal	2571
□	□	US 6472723 R1	20021029	12	Substrate contacts and shielding devices in a semiconductor device	2571
□	□	US 6489377	20021022	12	Semiconductor device with a substrate contact	2571